

IN THE CLAIMS

Please cancel claims 1-11 and 20-29 without prejudice.

1-11. (Cancelled)

12. (Original) A method comprising:

providing a first substrate;

predetermining a device placement location for a second substrate to be coupled to said first substrate;

predetermining a flow modifier height at least equal to a distance from a bottom surface of a second substrate used to couple said second substrate to said first substrate, to a top surface of said first substrate that is coupled to said second substrate;

coupling a flow modifier to said first substrate substantially around said device placement location and extending to a height substantially equal to said predetermined flow modifier height;

coupling said second substrate to said first substrate at said device placement location;

applying a first molding compound over said second substrate; and

applying a second molding compound between said first substrate and said second substrate.

13. (Original) The method of claim 12 wherein said flow modifier height is a distance approximately between 75 microns and 400 microns.

14. (Original) The method of claim 12 further comprising applying a low pressure over said substrates.

15. (Original) The method of claim 12 wherein said applying the first molding compound over said second substrate and applying said second molding compound between said first substrate and said second substrate happen at substantially the same time.

16. (Original) The method of claim 12 wherein applying said first molding compound over said second substrate happens before applying said second molding compound between said first substrate and said second substrate.

17. (Original) The method of claim 12 wherein applying said first molding compound over said second substrate happens after applying said second molding compound between said first substrate and said second substrate.

18. (Original) The method of claim 12 wherein the second substrate has not been coupled to said first substrate before said flow modifier is deposited.

19. (Original) The method of claim 12 wherein said flow modified is placed substantially around said device placement locations.

20-29. (Cancelled)

Pursuant to 37 C.F.R. 1.136(a)(3), applicant(s) hereby request and authorize the U.S. Patent and Trademark Office to (1) treat any concurrent or future reply that requires a petition for extension of time as incorporating a petition for extension of time for the appropriate length of time and (2) charge all required fees, including extension of time fees and fees under 37 C.F.R. 1.16 and 1.17, to Deposit Account No. 02-2666.

Respectfully submitted,

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